

## 1. Description

The HS25N06DA is the N-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other battery powered circuits, where high-side switching, and low in-line power loss are needed in a very small outline surface mount package.

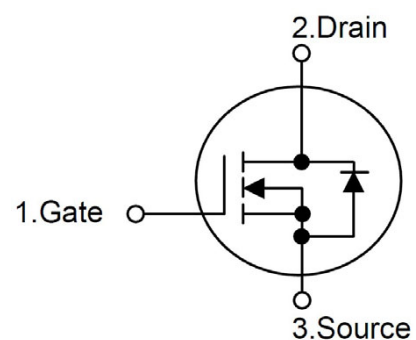
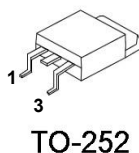
## 2. Feature

- $R_{DS(on)} \leq 62m\Omega @ V_{GS}=10V$
- $R_{DS(on)} \leq 86m\Omega @ V_{GS}=4.5V$
- Super high density cell design for extremely low  $R_{DS(on)}$
- Exceptional on-resistance and maximum DC current capability

$V_{DS}$	60	V
$R_{DS(on)}$	62	m $\Omega$
$I_D$	16	A

## 3. Pin configuration

Order Number	Package
HS25N06DA	TO-252



#### 4. Absolute maximum ratings (T<sub>A</sub>=25°C Unless Otherwise Noted)

Parameter		Symbol	Rating	Unit
Drain-Source Voltage		V <sub>DSS</sub>	60	V
Gate-Source Voltage		V <sub>GSS</sub>	±25	V
Continuous Drain Current(T <sub>J</sub> =150°C)	T <sub>C</sub> =25°C	I <sub>D</sub>	16	A
	T <sub>C</sub> =70°C		13	
Pulsed Drain Current		I <sub>DM</sub>	65	A
Maximum Power Dissipation	T <sub>C</sub> =25°C	P <sub>D</sub>	25	W
	T <sub>C</sub> =70°C		16	
Operating Junction Temperature		T <sub>J</sub>	-55 to 150	°C

#### 5. Thermal characteristics

Parameter	Symbol	Ratings	Units
Thermal resistance, case-to-sink typ.	R <sub>thCS</sub>	0.5	°C/W
Thermal resistance junction-case	R <sub>thJC</sub>	5	°C/W

**6. Electrical characteristics** ( $T_A=25^{\circ}\text{C}$  Unless Otherwise Specified)

Symbol	Parameter	Limit	Min	Typ	Max	Unit
<b>STATIC</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	60			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	1		3	V
$I_{GSS}$	Gate Leakage Current	$V_{DS}=0V, V_{GS}=\pm 25V$			$\pm 100$	nA
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=60V, V_{GS}=0V$			1	$\mu A$
		$V_{DS}=60V, V_{GS}=0V, T_J=55^{\circ}\text{C}$			10	
$R_{DS(ON)}$	Drain-Source On-Resistance <sup>a</sup>	$V_{GS}=10V, I_D=15A$		52	62	m $\Omega$
		$V_{GS}=4.5V, I_D=10A$		70	86	
$V_{SD}$	Diode Forward Voltage	$I_S=15A, V_{GS}=0V$		1		V
<b>DYNAMIC</b>						
$Q_g$	Total Gate Charge	$V_{DS}=48V, V_{GS}=10V, I_D=16A$		17		nC
$Q_{gs}$	Gate-Source Charge			4.2		
$Q_{gd}$	Gate-Drain Charge			5		
$R_g$	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$		0.6		$\Omega$
$C_{iss}$	Input Capacitance	$V_{DS}=30V, V_{GS}=0V,$ $f=1\text{MHz}$		523		pF
$C_{oss}$	Output Capacitance			47		
$C_{rss}$	Reverse Transfer Capacitance			14		
$t_{d(on)}$	Turn-On Delay Time	$V_{DD}=30V, R_L=15\Omega$ $I_D=1A, V_{GEN}=10V$ $R_G=3\Omega$		11		ns
$t_r$	Turn-On Rise Time			13		
$t_{d(off)}$	Turn-Off Delay Time			34		
$t_f$	Turn-Off Fall Time			4		

Notes :a. pulse test:pulse width $\leq 300\mu s$ ,duty cycle $\leq 2\%$  ,Guaranteed by design,not subject to production testing.

b.Homsemi reserves the right to improve product design,functions and reliability without notice.